Masked Autoencoder Self Pre-Training for Defect Detection in Microelectronics

Nikolai Röhrich^{1,2}, Alwin Hoffmann¹, Richard Nordsieck¹, Emilio Zarbali¹, and Alireza Javanmardi^{2,3}

¹ XITASO GmbH, Germany
 ² Institute of Informatics, LMU Munich, Germany
 ³ Munich Center for Machine Learning (MCML), Germany

Abstract. Whereas in general computer vision, transformer-based architectures have quickly become the gold standard, microelectronics defect detection still heavily relies on convolutional neural networks (CNNs). We hypothesize that this is due to the fact that a) transformers have an increased need for data and b) labelled image generation procedures for microelectronics are costly, and labelled data is therefore sparse. Whereas in other domains, pre-training on large natural image datasets can mitigate this problem, in microelectronics transfer learning is hindered due to the dissimilarity of domain data and natural images. Therefore, we evaluate self pre-training, where models are pre-trained on the target dataset, rather than another dataset. We propose a vision transformer (ViT) pre-training framework for defect detection in microelectronics based on masked autoencoders (MAE). In MAE, a large share of image patches is masked and reconstructed by the model during pre-training. We perform pre-training and defect detection using a dataset of less than 10.000 scanning acoustic microscopy (SAM) images labelled using transient thermal analysis (TTA). Our experimental results show that our approach leads to substantial performance gains compared to a) supervised ViT, b) ViT pre-trained on natural image datasets, and c) state-of-theart CNN-based defect detection models used in the literature. Additionally, interpretability analysis reveals that our self pre-trained models, in comparison to ViT baselines, correctly focus on defect-relevant features such as cracks in the solder material. This demonstrates that our approach yields fault-specific feature representations, making our self pretrained models viable for real-world defect detection in microelectronics.

Keywords: Masked Autoencoder \cdot Vision Transformer \cdot Pretraining \cdot Microelectronics \cdot LED \cdot Solder Joint \cdot Quality Control

1 Introduction

Reliable solder joints are crucial for the continued miniaturization and enhanced functionality of microelectronics, with applications spanning consumer electronics, automotive systems, healthcare, and defense [25]. Defect detection in microelectronics often relies on images, which are obtained by intricate procedures



Fig. 1: **Masked Autoencoder Framework.** In MAE pre-training, a large share (e.g. 75%) of input patches is masked. The encoder (ENC) then performs self-attention for visible patches only. After adding mask-tokens, which serve as place-holders for missing inputs, the decoder (DEC) reconstructs the complete image. Thereby, the model learns meaningful representations of input data.

like scanning microscopy or X-ray imaging. Image data are then used in smart manufacturing processes such as Automated Optical Inspection (AOI) to ensure product reliability and performance [1,31].

In particular, deep learning based vision models have recently shown strong performance in AOI tasks like defect detection [41,42,27,18]. While convolutional neural networks (CNNs) have traditionally been the dominant choice for deep learning based computer vision, vision transformer (ViT) models have recently emerged as the gold standard in the field [20,22,35]. However, the application of transformer models to defect detection in microelectronics remains underexplored, with the field often relying on conventional CNNs and recent survey studies sometimes not mentioning transformer models at all [27,18]. One main reason for this could be that training transformers from scratch usually requires a large amount of data [40,13,46]. In microelectronics manufacturing - especially for microscale solder joints - labelled image data collection often relies on expensive procedures, resulting in small and imbalanced datasets [1]. Additionally, fine-tuning transformers pre-trained on large datasets usually requires at least some similarity between the pre-training domain and the target domain [2]. This circumstance is problematic for microelectronics since most pre-trained transformers are trained on natural image datasets like ImageNet [11] that are highly dissimilar from target datasets in this domain (see Figure 2).

Inspired by other domains facing similar challenges, such as healthcare, this paper explores the potential of a pure transformer model for microelectronics defect detection by leveraging self pre-training, where models are pre-trained directly on the target dataset rather than an extensive natural image dataset [50]. Specifically, we use masked autoencoders (MAEs) [16], which mask a large share of image patches and task the model with reconstructing the missing inputs (see Figure 1). MAEs are resource-efficient and well-suited for smaller datasets, as they do not require large batch sizes like contrastive pre-training approaches. Additionally, the repeated randomized masking of different image patches presents the autoencoder with diverse reconstruction tasks, even with limited data. Us-



(b) Scanning Acoustic Microscopy images from our target dataset [31].

Fig. 2: Domain gap between natural images and images from our target domain.

ing a dataset of less than 10.000 scanning acoustic microscopy (SAM) images of microscale LED solder joints labelled using transient thermal analysis (TTA), we compare our approach to a) purely supervised ViT, b) ViT pre-trained on a natural image dataset, and c) state-of-the-art CNN architectures proposed in the literature on industrial defect detection. In particular, we fine-tune our models for a regression task where models predict how far a given LED is from failure.

Contributions Our experimental findings indicate that, with our approach, models learn generalizable representations in self pre-training that yield substantial performance increases in defect detection for microelectronics. In particular, our model outperforms a) purely supervised ViTs by 21.1%, b) ViTs pre-trained on Imagenet by 10.2% and c) state-of-the-art CNN defect detection models by 5.3%. Also, we find that our models learn fault-specific representations, focusing on actual damages in the solder material when performing defect detection, while other ViT models have scattered attention or learn shortcuts. In addition, due to the simplicity and low data requirements of our framework, it can be easily integrated into real-world inline quality control procedures such as AOI.

2 Related Work

Vision Transformer ViT [13] is a vision adaption of the self-attention based transformer architecture [40], which constitutes the backbone of large language models. ViT has demonstrated effectiveness across various vision tasks, including image classification, object detection, and segmentation [19,33,37]. Related research on ViT includes domain-specific fine-tuning of foundational models and architectural adaptions that aim at improved domain generalization or increased data efficiency: Alijiani et al. [2] discuss various ViT domain adaption and generalization approaches on the feature extraction level, the instance level and the model architecture level. Papa et al. [26] compare ViT approaches aiming at increased data efficiency, such as Data Efficient Transformers (DeiT) [38,39] or Shifted Window Transformers (Swin) [21]. Since we leverage representations learned in pre-training, our approach is similar to domain specific fine-tuning.

However, our framework differs from such approaches since we pre-train ViT from scratch on the target dataset, rather than using foundational models pre-trained on large natural image datasets.

Self-Supervised Learning SSL aims to learn meaningful representations from data without labels. Instead of labels, intrinsic relationships of the data serve as guidance for the training process. Balestriero et al. [3] distinguish four sub-types of SSL approaches: (1) deep metric learning approaches such as SimCLR [10] or NNCLR [14], where models recognize similarity in differently transformed inputs, (2) self-distillation learning approaches like BYOL [15], SimSIAM [9] or DINO [7], where different input transforms serve as inputs into two separate encoders before letting one serve as a predictor of the other's output, (3) canonical correlation analysis approaches such as VICReg [5], BarlowTwins [45] or SWAV [6], which are founded on the principle of understanding relationships between two variables by examining their cross-covariance matrices and (4) masked image modelling (MIM) approaches like SimMIM [43], where images undergo partial masking and models reconstruct the missing inputs. We follow the MIM approach due to its simplicity, efficacy, and low data requirements.

In MIM, iGPT [8] first demonstrated the potential of applying masked language modeling strategies to the vision domain by predicting masked pixels in a sequence-like manner. ViT [13] then demonstrated the practical applicability of MIM pre-training in vision by extending masked prediction from pixels to image patches, emphasizing the spatial locality of image data. BEiT [4] introduced a discrete token prediction objective analogous to masked language modeling in NLP and showed that visual tokens enhance pre-training for image-related tasks. In MAE [16], an encoder receives a $\approx 25\%$ share of unmasked patches as input, and a lightweight decoder reconstructs the full image (see Figure 1). MAE pre-training has been demonstrated to achieve state-of-the-art performance with minimal data and compute requirements [47]. Our approach is a variation of the work by He et al. [16] but optimizes the framework for the given use case.

Microelectronics Quality Control In microelectronics research and manufacturing, image-based quality control procedures like AOI are standard practice [1]. Deep learning based approaches have significantly advanced the field in recent years, including but not limited to the subdomain of solder joints [41,42,27,18]. Samavatian et al. [29] present an iterative machine learning framework that enhances the accuracy of solder joint lifetime prediction by utilizing a self-healing dataset iteratively injected into a correlation-driven neural network (CDNN). Salameh et al. [28] demonstrate the use of deep neural networks, combined with finite element simulations, as a rapid and comprehensive tool for solder joint reliability analysis under mechanical loading. Muench et al. [24] propose a methodology for predicting damage progression in solder contacts and compare an MLP network with a long short-term memory (LSTM) model using production-like synthetic data. Zhang et al. [48] employ various deep learning models, including CNN and LSTM models, for automatic solder joint defect detection using X-ray Table 1: **Dataset.** Repeated cooling and heating of LED solder joints simulates aging through thermomechanical fatigue. Over time, cracks gradually emerge, impeding the heat flow through the solder material. ΔB_{max} values indicate relative degradation and LEDs with $\Delta B_{max} > 20\%$ are classified as defective (*).



images. Zhang et al. [49] combine CNN and transformer components in a model intended for printed control board solder joints. However, Zhang et al. use transformer blocks only as small parts of their network aided by convolutional layers and report poor performances for pure transformer models [49]. We believe that this is due to a lack of domain-specific pre-training. Our approach, in contrast, demonstrates the potential of pure transformer architectures for defect detection without architectural crutches like CNN layers.

3 Dataset

We use scanning acoustic microscopy (SAM) images and transient thermal analysis (TTA) measurements from a dataset of microscale solder joints of high-power LEDs [31], which is publicly available on Kaggle [30]. The dataset contains SAM and TTA data for 1.800 LEDs at 5 points of time, with nine LED types and five lead-free solder pastes. To simulate ageing, LED panels underwent thermal shock cycles (TSC) from -40° C to 125° C, a standard quality control process to evaluate the reliability and durability of solder joints under extreme conditions. We use a train, validation and test split of 60%, 20% and 20% respectively. All reported metrics and all shown example outputs refer to the test dataset.

3.1 Scanning Acoustic Microscopy (SAM)

We use SAM images for pre-training and as model inputs in downstream tasks. SAM imaging offers detailed information on material interfaces, allowing the detection of critical defects such as voids, cracks, and delaminations within solder 6 Röhrich et al.

joints [23]. SAM images were taken after 0, 100, 500, 1.000, and 1.500 TSC, resulting in 5 images per LED and 9.000 images in total (see Table 1). The original SAM images contain 2 LEDs and are cropped so that each image shows an individual solder joint. All images are resized to a $64 \times 64 \times 1$ pixel format. For each LED image, bright boundary regions depict gaps between the darker solder pads. On the solder pads, small circles indicate voids in the solder material, from which cracks can emerge over time. Bright, non-circular structures inside the pads are cracks in the solder material (see Table 1).

3.2 Transient Thermal Analysis (TTA)

We use TTA data to create labels indicating how far LEDs depicted in SAM images are from failure. TTA is a non-destructive test method that quantifies the integrity of the thermal path from the LED junction to the heat sink through the solder joint [51]. Defects such as cracks impede the heat flow through the solder by reducing the size of the contact area. In TTA, the thermal impedance $Z_{th}(t)$ is measured, which describes the temperature difference at the LED junction over time compared to the change in power. Any degradation results in an increase in $Z_{th}(t)$. For a quantitative comparison of TTA measurements between different TSCs, the maximum value B_{max} of the normalized logarithmic derivative B(t') of the thermal impedance $Z_{th}(t)$ with t' = ln(t) is used [52]. As B_{max} increases in case of degradation, the relative increase in B_{max} at cycle t compared to the initial state $\Delta B_{max}(t)$ serves as the basis for image labelling:

$$\Delta B_{max}(t) = \frac{B_{max}(t)}{B_{max}(0)} - 1. \tag{1}$$

While we use numerical labels to achieve a continuous representation of an LED's current quality, an LED with $\Delta B_{max} > 20\%$ is classified as defective [44].

4 Method

4.1 Preliminaries

Vision Transformer Transformer processing employs multi-head self-attention (MSA) on sequential inputs [40]. For the sequentialization of 2D images, images are divided into smaller patches and are linearly projected into the embedding space. Let H_i, W_i be the height and width of the original image, and let H_p, W_p be the patch height and width, where usually image patches are quadratic, i.e. $H_p = W_p =: P$ (*). The image is then divided into

$$N = \frac{H_i \cdot W_i}{H_p \cdot W_p} \stackrel{*}{=} \frac{H_i \cdot W_i}{P^2} \tag{2}$$

patches. After flattening and applying a linear mapping $E \in \mathbb{R}^{P^2 \times D}$ to project the patch into the embedding space \mathbb{R}^D , positional embeddings $E_{pos} \in \mathbb{R}^{N \times D}$ are

Table 2: ViT Sizes. While all of the evaluated sizes use 12 transformer blocks, they differ in token length (width) and the number of heads used for MSA.

Model	Layers	Width	Heads	Params
ViT-Ti	12	192	3	$5.7 \mathrm{M}$
ViT-S	12	384	6	$22.1 \mathrm{~M}$
ViT-B	12	768	12	$86.7~{\rm M}$

added to the elements of the sequence to retain the spatial location of each patch embedding. Lastly, a learnable class token x_{class} is prepended to the sequence to store global information during processing. Images are thus transformed into a sequence X of N + 1 embeddings, which serve as tokens for MSA:

$$X = [x_{class}, Ex_1 + E_{pos,1}, \dots, Ex_N + E_{pos,N}] \subseteq \mathbb{R}^D$$
(3)

Depending on the ViT size, the sequence passes through several MSA blocks. Since we are working with relatively small $64 \times 64 \times 1$ shaped images, we use ViT sizes tiny, small, and base for determining the number of transformer blocks, the token length, and the number of heads (see Table 2). In the original ViT [13], the output class token is fed into a single linear layer for classification. We find that using a larger classification head increases performance and thus use a multi-layered dense network with a hidden dimension of 2048.

Masked Autoencoder Pre-Training For MAE pre-training, a ViT encoder combined with a lightweight transformer decoder is tasked with reconstructing missing image patches (see Figure 1). Depending on the masking share S, which is usually 0.75, a random subset M of $\lfloor N \cdot S \rfloor$ indexes is sampled from the set of indexes $I = \{1, \ldots, N\}$ without replacement. X is split into a set of masked patches X_M and a set of visible patches $X_{I\setminus M}$. Note that X_M and $X_{I\setminus M}$ are absolute complement with respect to X_I , i.e. $X_m \cup X_{I\setminus M} = X_I$ and $X_m \cap X_{I\setminus M} = \emptyset$. After masking, the sequence consists of $\lfloor N \cdot S \rfloor$ embeddings:

$$X = [\tilde{x}_1 E + E_{pos,1}, \dots, \tilde{x}_{|N \cdot S|} E + E_{pos,|N \cdot S|}] \subseteq \mathbb{R}^D$$

$$\tag{4}$$

Inputs are then fed into the autoencoder network. The MAE encoder operates only on the visible patches, i.e. on a 1-S share of the total input patches. The decoder, in contrast, receives as input a full sequence of tokens including a) the embeddings of visible patches and b) mask tokens, which are shared and learnable embeddings serving as placeholders for masked patches, similar to BERT [12]. The model minimizes the pixel-wise MSE loss for masked patches with respect to its parameters θ . The loss is computed for masked patches only, i.e. for $k \in M$:

$$\min_{\theta} \mathcal{L}_{mae}(X, M, \theta) = \sum_{k \in M} \|y_k - x_k\|_2^2$$
(5)

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(a) Patch Sizes		(b) Mask	(c) A	(c) Augmentations		
Patch Size	$\mathrm{MSE}\downarrow$	Mask Ratio	$\mathrm{MSE}\downarrow$	Augment	tations	$\mathrm{MSE}\downarrow$
4×4	0.0186	70%	0.0175	horizont	al flip	0.0190
8×8	0.0167	75%	0.0167	vertica	l flip	0.0189
16×16	0.0197	80%	0.0188	\mathbf{bot}	h	0.0179
				crop (rai	ndom)	0.0185
				crop (f	ixed)	0.0176

Table 3: Hyperparameter tuning for patch size, mask ratio, and augmentations.

5 Experiments

5.1 Hyperparameter Tuning

Because of the different structure of SAM images and due to the smaller image size compared to standard datasets like ImageNet, we hypothesize that smaller patch sizes, different augmentations, and different mask ratios than those used for standard ViT could achieve optimal performance. To evaluate hyperparameter settings, we pre-train models with MAE for 200 epochs on our dataset, and fine-tune for defect detection for 100 epochs.

Results are shown in Table 3. Although we find that, consistent with the results for ImageNet, a mask ratio of 75% works best, our hypothesis was confirmed for patch size and augmentations: For image patches, a size of 8×8 worked best, while typically, a patch size of 16×16 is used. Notably, the found optimal image to patch size ratio of 64 : 8 = 8 also differs from the standard ratio of 224 : 16 = 14 used for datasets like ImageNet [13]. We assume that this non-linear dependence between image size and optimal patch size is explained by the fact that once patches get too small, a single patch does not contain enough localized information for a meaningful computation of self-attention.

For augmentations, a combination of horizontal and vertical flipping and fixed-size cropping achieved the best results, while for ImageNet horizontal flipping and random-sized cropping are used [13]. In contrast to natural images, vertical flipping is a valid augmentation for microelectronics, where image orientation is not relevant. Also, we suspect that fixed-size cropping works best since random-sized crops of 64×64 images suffer greater quality loss by resizing operations than the 224×224 images in standard large datasets like ImageNet.

5.2 MAE Self Pre-Training

We conduct MAE pre-training on the target SAM image dataset, utilizing the hyperparameters optimized through our previous studies. MAE with ViT encoders of sizes Ti, S, and B are pre-trained for 1.000 epochs on two L40S GPUs respectively. In Figure 3, we plot the MSE reconstruction loss for masked input patches \mathcal{L}_{mae} for each model size. Notably, the S-sized encoder achieved the



Fig. 3: MAE Pre-Training.

worst performance in reconstruction, although having more parameters than the Ti-sized encoder. However, the even larger B-sized encoder significantly outperformed all smaller sizes. We take this to indicate that a) for smaller images, even very small encoders like ViT-Ti can achieve good results and that b) there is a non-linear relationship between model capacity and performance. For smaller datasets like ours, there appears to be a critical threshold where increased model complexity transitions from potentially harmful (due to overfitting) to beneficial. Although ViT-B achieved the best results overall, ViT-Ti could be the model of choice in resource-critical applications.

Exemplary reconstructions from the test set using the best-performing ViT-B encoder are shown in Figure 4. We find that after training, the autoencoder produces high-quality reconstructions for all LED types, indicating that it learned meaningful representations of the dataset. In particular, the model is able to reconstruct masked inputs at varying amounts of TSC, accurately predicting the expansion of cracks even in masked regions (see Figure 4 (b)).

5.3 Defect Detection

For inline automated optical inspection in microelectronics manufacturing, defect detection is a common practice. We perform defect detection given an input image using the ΔB_{max} values given by TTA as labels. While an LED with ΔB_{max} larger than 20% is classified as faulty, we predict the scalar ΔB_{max} values directly to have a continuous measure for LED quality. That is, having the model predict ΔB_{max} not only indicates whether the given LED is functional, but also how far the LED is from failure. We compare ViT pre-trained with our MAE-based framework for 1.000 epochs against purely supervised ViT and ViT pre-trained with ImageNet. Also, we compare our models against large standard CNN backbones like ResNet [17], EfficientNet [36] or VGG [34] as well as against recent CNN architectures specifically designed for defect detection in microelec-



Fig. 4: **MAE Reconstructions.** For (a) TSC 0 and (b) TSC 1500, original images, masked inputs, and the model's reconstructions are depicted.

tronics. In particular, we evaluate the model by Zippelius et al. [52] intended for SAM images of solder joints as well as the model by Zhang et al. [48] intended for X-ray images of solder joints. All models are trained for up to 200 epochs.

We find that ViT pre-trained with our self pre-training framework outperforms all other CNN and transformer-based models, achieving an MSE improvement of 5.30% compared to the best-performing baseline (see Table 4). When it comes to other ViT models, our model outperforms purely supervised ViTs by 21.1% and ViTs pre-trained on Imagenet by 10.2%. Notably, while the best results are achieved by the largest self pre-trained transformer model, ViT-Ti already outperforms considerably larger baselines by 3.20% with only 5.7 million parameters. Thus, ViT self pre-trained with MAE not only substantially outperforms other ViT models and state-of-the-art CNN defect detection models, but is already able to do so using the smallest available architecture size.

In contrast to our self pre-trained models however, we find that purely supervised ViT performs poorly compared to all other models due to the lack of pre-training and the small amount of target data, which is consistent with earlier findings [49]. What is more, we find that MAE pre-training using ImageNet increases performance compared to purely supervised ViT, but cannot outperform convolutional baselines. This suggests that for applications with even less data than in our case, fine-tuning foundational vision models or using convolutional defect detection architectures might remain a valid option.

We perform interpretability analysis with class activation maps using Grad-CAM [32]. In GradCAM, the relevance of image regions for the output is visualized by computing gradients of the output with respect to a given layer. We choose the first norm layer of the last transformer block for the gradient computation. Results for all ViT-B variants are shown in Figure 5. We find that:

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Model	Method	Params	MSE	Δ to Best
SAM-CNN [52]	supervised	4.2 M	0.0336	10.5%
XRAY-CNN [48]	supervised	$8.7 \mathrm{M}$	0.0337	10.9%
ResNet50 [17]	supervised	$23.5 \mathrm{M}$	0.0339	11.5%
EfficientNet-B7 [36]	supervised	$63.8 \mathrm{M}$	0.0331	8.9%
VGG-11 [34]	supervised	$128.8~\mathrm{M}$	0.0320	5.3%
ViT-Ti [13]	supervised	$5.7 \mathrm{M}$	0.0380	25.0%
ViT-S [13]	supervised	$22.1 \mathrm{M}$	0.0368	21.1%
ViT-B [13]	supervised	$86.7~{\rm M}$	0.0380	25.0%
ViT-Ti [13]	MAE (ImageNet)	$5.7 \mathrm{M}$	0.0345	13.4%
ViT-S [13]	MAE (ImageNet)	$22.1 \mathrm{M}$	0.0339	11.5%
ViT-B [13]	MAE (ImageNet)	$86.7~{\rm M}$	0.0335	10.2%
ViT-Ti (ours)	MAE (self)	5.7 M	0.0310	2.0%
ViT-S (ours)	MAE (self)	$22.1 \mathrm{M}$	0.0335	10.2%
ViT-B (ours)	MAE (self)	$86.7~\mathrm{M}$	0.0304	-

Table 4: **Defect Detection.** All models are trained for 200 epochs on the SAM dataset. We report mean squared error (MSE) scores on the test set, where a lower score is better. Also, we report the percental differences to the best model.

- 1. Supervised ViT-B has scattered attention for both early and late TSC (see Figure 5), indicating that the transformer encoder does not learn meaningful representations in purely supervised training.
- 2. ViT-B pre-trained on ImageNet strongly focuses on the bright bounding regions between solder pads, indicating that the model attends to the LED type, even when clear defects such as cracks in the solder material are visible (see Figure 5 (b), row 3 and 4). We interpret this as the model learning a shortcut rather than the actual dependency between defects like cracks in the solder material and ΔB_{max} .
- 3. ViT-B self pre-trained on SAM data solely attends to actual defects such as cracks for later TSC with stronger degradation (Figure 5 (b)) and attends to voids and the boundary regions between solder pads if no damages are visible (Figure 5 (a)). This indicates that the model prioritizes actual defects and considers the general error-proneness of different LED types when no defects are visible.

Thus, our findings indicate that MAE self pre-training yields superior representations for defect detection compared to supervised training and pre-training on natural image data. This confirms our hypothesis that domain-specific pretraining can account for the data requirements of transformers under the data sparsity in microelectronics.



Fig. 5: Attention Visualization. Compared to supervised ViT-B and ViT-B pre-trained with MAE on ImageNet, our model self pre-trained with MAE focuses on the LED type and on voids in the solder material for earlier TSC (a), and on defects such as cracks for later TSC (b), indicating that MAE self pre-training yields superior and defect-specific feature representations.

6 Discussion and Conclusion

In this paper, we employ vision transformers self pre-trained using maskedautoencoders for defect detection in microelectronics. Our methodology leverages the strong predictive capabilities of transformers while adapting to our specific target domain despite limited labeled data. For defect detection on a small dataset of microscale solder joints of high-power LEDs, our approach demonstrates superior performance compared to various state-of-the-art CNN-based architectures and other transformer baselines.

The demonstrated effectiveness of our approach has broad implications for quality control in Industry 4.0 settings, where maximizing production yield while minimizing the cost and time required for inspection remains a central challenge. By enabling more accurate detection of developing solder joint defects in early stages, our approach can reduce warranty costs, improve product reliability, and increase customer satisfaction. As manufacturing processes continue to demand higher precision and reliability while dealing with ever-increasing miniaturization, approaches like ours that can leverage limited domain data effectively will become increasingly valuable. The combination of high accuracy, interpretability, and resource efficiency positions our MAE self pre-training framework as a promising path forward for next-generation quality inspection systems in microelectronics, with particular potential for integration into capable smart sensors that enable real-time defect detection directly on the production line.

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References

- Abd Al Rahman, M., Mousavi, A.: A review and analysis of automatic optical inspection and quality monitoring methods in electronics industry. IEEE Access 8, 183192–183271 (2020)
- Alijani, S., Fayyad, J., Najjaran, H.: Vision transformers in domain adaptation and generalization: A study of robustness. arXiv e-prints pp. arXiv-2404 (2024)
- Balestriero, R., Ibrahim, M., Sobal, V., Morcos, A., Shekhar, S., Goldstein, T., Bordes, F., Bardes, A., Mialon, G., Tian, Y., et al.: A cookbook of self-supervised learning. arXiv preprint arXiv:2304.12210 (2023)
- Bao, H., Dong, L., Piao, S., Wei, F.: Beit: Bert pre-training of image transformers. arXiv preprint arXiv:2106.08254 (2021)
- Bardes, A., Ponce, J., LeCun, Y.: Vicreg: Variance-invariance-covariance regularization for self-supervised learning. arXiv preprint arXiv:2105.04906 (2021)
- Caron, M., Misra, I., Mairal, J., Goyal, P., Bojanowski, P., Joulin, A.: Unsupervised learning of visual features by contrasting cluster assignments. Advances in neural information processing systems 33, 9912–9924 (2020)
- Caron, M., Touvron, H., Misra, I., Jégou, H., Mairal, J., Bojanowski, P., Joulin, A.: Emerging properties in self-supervised vision transformers. In: Proceedings of the IEEE/CVF international conference on computer vision. pp. 9650–9660 (2021)
- Chen, M., Radford, A., Child, R., Wu, J., Jun, H., Luan, D., Sutskever, I.: Generative pretraining from pixels. In: International conference on machine learning. pp. 1691–1703. PMLR (2020)
- Chen, T., Kornblith, S., Norouzi, M., Hinton, G.: A simple framework for contrastive learning of visual representations. In: International conference on machine learning. pp. 1597–1607. PmLR (2020)
- Chen, X., He, K.: Exploring simple siamese representation learning. In: Proceedings of the IEEE/CVF conference on computer vision and pattern recognition. pp. 15750–15758 (2021)
- Deng, J., Dong, W., Socher, R., Li, L.J., Li, K., Fei-Fei, L.: Imagenet: A largescale hierarchical image database. In: 2009 IEEE conference on computer vision and pattern recognition. pp. 248–255. IEEE (2009)
- Devlin, J., Chang, M.W., Lee, K., Toutanova, K.: Bert: Pre-training of deep bidirectional transformers for language understanding. In: Proceedings of the 2019 conference of the North American chapter of the association for computational linguistics: human language technologies, volume 1 (long and short papers). pp. 4171–4186 (2019)

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- Dosovitskiy, A., Beyer, L., Kolesnikov, A., Weissenborn, D., Zhai, X., Unterthiner, T., Dehghani, M., Minderer, M., Heigold, G., Gelly, S., et al.: An image is worth 16x16 words: Transformers for image recognition at scale. arXiv preprint arXiv:2010.11929 (2020)
- Dwibedi, D., Aytar, Y., Tompson, J., Sermanet, P., Zisserman, A.: With a little help from my friends: Nearest-neighbor contrastive learning of visual representations. In: Proceedings of the IEEE/CVF international conference on computer vision. pp. 9588–9597 (2021)
- Grill, J.B., Strub, F., Altché, F., Tallec, C., Richemond, P., Buchatskaya, E., Doersch, C., Avila Pires, B., Guo, Z., Gheshlaghi Azar, M., et al.: Bootstrap your own latent-a new approach to self-supervised learning. Advances in neural information processing systems 33, 21271–21284 (2020)
- He, K., Chen, X., Xie, S., Li, Y., Dollár, P., Girshick, R.: Masked autoencoders are scalable vision learners. In: Proceedings of the IEEE/CVF conference on computer vision and pattern recognition. pp. 16000–16009 (2022)
- He, K., Zhang, X., Ren, S., Sun, J.: Deep residual learning for image recognition. In: Proceedings of the IEEE conference on computer vision and pattern recognition. pp. 770–778 (2016)
- Islam, M.R., Zamil, M.Z.H., Rayed, M.E., Kabir, M.M., Mridha, M., Nishimura, S., Shin, J.: Deep learning and computer vision techniques for enhanced quality control in manufacturing processes. IEEE Access (2024)
- Khalil, M., Khalil, A., Ngom, A.: A comprehensive study of vision transformers in image classification tasks. arXiv preprint arXiv:2312.01232 (2023)
- Khan, A., Rauf, Z., Sohail, A., Khan, A.R., Asif, H., Asif, A., Farooq, U.: A survey of the vision transformers and their cnn-transformer based variants. Artificial Intelligence Review 56(Suppl 3), 2917–2970 (2023)
- Liu, Z., Lin, Y., Cao, Y., Hu, H., Wei, Y., Zhang, Z., Lin, S., Guo, B.: Swin transformer: Hierarchical vision transformer using shifted windows. In: Proceedings of the IEEE/CVF international conference on computer vision. pp. 10012–10022 (2021)
- Maurício, J., Domingues, I., Bernardino, J.: Comparing vision transformers and convolutional neural networks for image classification: A literature review. Applied Sciences 13(9), 5521 (2023)
- 23. Mehr, M.Y., Bahrami, A., Fischer, H., Gielen, S., Corbeij, R., Van Driel, W., Zhang, G.: An overview of scanning acoustic microscope, a reliable method for non-destructive failure analysis of microelectronic components. In: 2015 16th International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Microelectronics and Microsystems. pp. 1–4. IEEE (2015)
- Muench, S., Bhat, D., Heindel, L., Hantschke, P., Roellig, M., Kaestner, M.: Performance assessment of different machine learning algorithm for life-time prediction of solder joints based on synthetic data. In: 2022 23rd International Conference on Thermal, Mechanical and Multi-Physics Simulation and Experiments in Micro-electronics and Microsystems (EuroSimE). pp. 1–10. IEEE (2022)
- Njoku, J.E., Amalu, E.H., Ekere, N., Mallik, S., Ekpu, M., Ogbodo, E.A.: Effects of reflow profile and miniaturisation on the integrity of solder joints in surface mount chip resistors. Journal of Electronic Materials 52(6), 3786–3796 (2023)
- Papa, L., Russo, P., Amerini, I., Zhou, L.: A survey on efficient vision transformers: algorithms, techniques, and performance benchmarking. IEEE Transactions on Pattern Analysis and Machine Intelligence (2024)
- Saberironaghi, A., Ren, J., El-Gindy, M.: Defect detection methods for industrial products using deep learning techniques: A review. Algorithms 16(2), 95 (2023)

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- Salameh, A.A., Hosseinalibeiki, H., Sajjadifar, S.: Application of deep neural network in fatigue lifetime estimation of solder joint in electronic devices under vibration loading. Welding in the World 66(10), 2029–2040 (2022)
- Samavatian, V., Fotuhi-Firuzabad, M., Samavatian, M., Dehghanian, P., Blaabjerg, F.: Iterative machine learning-aided framework bridges between fatigue and creep damages in solder interconnections. IEEE Transactions on Components, Packaging and Manufacturing Technology 12(2), 349–358 (2021)
- Schmid, M., Zippelius, A., Elger, G.: Reliability of high-power leds and solder pastes (2023), https://www.kaggle.com/ds/2203337
- Schmid, M., Zippelius, A., Hanß, A., Böckhorst, S., Elger, G.: Investigations on high-power leds and solder interconnects in automotive application: Part i—initial characterization. IEEE Transactions on Device and Materials Reliability 22(2), 175–186 (2022)
- Selvaraju, R.R., Cogswell, M., Das, A., Vedantam, R., Parikh, D., Batra, D.: Gradcam: Visual explanations from deep networks via gradient-based localization. In: Proceedings of the IEEE international conference on computer vision. pp. 618–626 (2017)
- Shehzadi, T., Hashmi, K.A., Stricker, D., Afzal, M.Z.: Object detection with transformers: A review. arXiv preprint arXiv:2306.04670 (2023)
- Simonyan, K., Zisserman, A.: Very deep convolutional networks for large-scale image recognition. arXiv preprint arXiv:1409.1556 (2014)
- 35. Takahashi, S., Sakaguchi, Y., Kouno, N., Takasawa, K., Ishizu, K., Akagi, Y., Aoyama, R., Teraya, N., Bolatkan, A., Shinkai, N., et al.: Comparison of vision transformers and convolutional neural networks in medical image analysis: a systematic review. Journal of Medical Systems 48(1), 84 (2024)
- Tan, M., Le, Q.: Efficientnet: Rethinking model scaling for convolutional neural networks. In: International conference on machine learning. pp. 6105–6114. PMLR (2019)
- Thisanke, H., Deshan, C., Chamith, K., Seneviratne, S., Vidanaarachchi, R., Herath, D.: Semantic segmentation using vision transformers: A survey. Engineering Applications of Artificial Intelligence 126, 106669 (2023)
- Touvron, H., Cord, M., Douze, M., Massa, F., Sablayrolles, A., Jégou, H.: Training data-efficient image transformers & distillation through attention. In: International conference on machine learning. pp. 10347–10357. PMLR (2021)
- Touvron, H., Cord, M., Jégou, H.: Deit iii: Revenge of the vit. In: European conference on computer vision. pp. 516–533. Springer (2022)
- Vaswani, A., Shazeer, N., Parmar, N., Uszkoreit, J., Jones, L., Gomez, A.N., Kaiser, L., Polosukhin, I.: Attention is all you need. Advances in neural information processing systems **30** (2017)
- Villalba-Diez, J., Schmidt, D., Gevers, R., Ordieres-Meré, J., Buchwitz, M., Wellbrock, W.: Deep learning for industrial computer vision quality control in the printing industry 4.0. Sensors 19(18), 3987 (2019)
- Wang, Y., Zhao, Y., Addepalli, S.: Remaining useful life prediction using deep learning approaches: A review. Procedia manufacturing 49, 81–88 (2020)
- 43. Xie, Z., Zhang, Z., Cao, Y., Lin, Y., Bao, J., Yao, Z., Dai, Q., Hu, H.: Simmim: A simple framework for masked image modeling. In: Proceedings of the IEEE/CVF conference on computer vision and pattern recognition. pp. 9653–9663 (2022)
- 44. Zarbali, E., Hoffmann, A., Hepp, J.: Contrastive pretraining of regression tasks in reliability forecasting of automotive electronics. In: 2023 International Conference on Machine Learning and Applications (ICMLA). pp. 332–338. IEEE (2023)

- 16 Röhrich et al.
- Zbontar, J., Jing, L., Misra, I., LeCun, Y., Deny, S.: Barlow twins: Self-supervised learning via redundancy reduction. In: International conference on machine learning. pp. 12310–12320. PMLR (2021)
- Zhai, X., Kolesnikov, A., Houlsby, N., Beyer, L.: Scaling vision transformers. In: Proceedings of the IEEE/CVF conference on computer vision and pattern recognition. pp. 12104–12113 (2022)
- 47. Zhang, C., Zhang, C., Song, J., Yi, J.S.K., Kweon, I.S.: A survey on masked autoencoder for visual self-supervised learning. In: IJCAI. pp. 6805–6813 (2023)
- Zhang, Q., Zhang, M., Gamanayake, C., Yuen, C., Geng, Z., Jayasekara, H., Woo, C.w., Low, J., Liu, X., Guan, Y.L.: Deep learning based solder joint defect detection on industrial printed circuit board x-ray images. Complex & Intelligent Systems 8(2), 1525–1537 (2022)
- Zhang, Z., Zhang, W., Zhu, D., Xu, Y., Zhou, C.: Printed circuit board solder joint quality inspection based on lightweight classification network. IET Cyber-Systems and Robotics 5(4), e12101 (2023)
- Zhou, L., Liu, H., Bae, J., He, J., Samaras, D., Prasanna, P.: Self pre-training with masked autoencoders for medical image classification and segmentation. In: 2023 IEEE 20th International Symposium on Biomedical Imaging (ISBI). pp. 1–6. IEEE (2023)
- Zippelius, A., Hanß, A., Schmid, M., Pérez-Velázquez, J., Elger, G.: Reliability analysis and condition monitoring of sac+ solder joints under high thermomechanical stress conditions using neuronal networks. Microelectronics Reliability 129, 114461 (2022)
- 52. Zippelius, A., Strobl, T., Schmid, M., Hermann, J., Hoffmann, A., Elger, G.: Predicting thermal resistance of solder joints based on scanning acoustic microscopy using artificial neural networks. In: 2022 IEEE 9th Electronics System-Integration Technology Conference (ESTC). pp. 566–575. IEEE (2022)